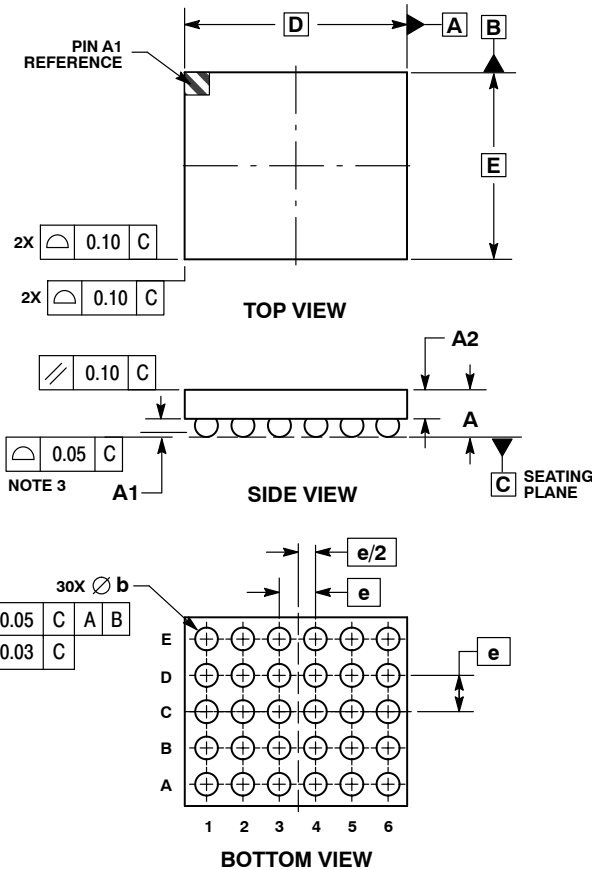




SCALE 4:1

**WLCSP30, 2.46x2.06**  
CASE 567CU  
ISSUE A

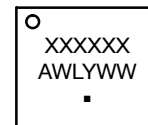
DATE 30 JUN 2011



## NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.

MILLIMETERS		
DIM	MIN	MAX
A	---	0.60
A1	0.17	0.23
A2	0.33	0.39
b	0.24	0.29
D	2.46 BSC	
E	2.06 BSC	
e	0.40 BSC	

**GENERIC MARKING DIAGRAM\***


XXXXXX= Specific Device Code

A = Assembly Location

WL = Wafer Lot

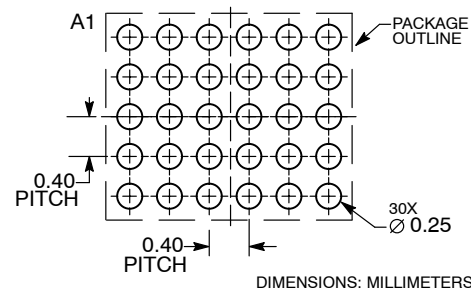
Y = Year

WW = Work Week

▪ = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking.

Pb-Free indicator, "G" or microdot "▪", may or may not be present.

**RECOMMENDED SOLDERING FOOTPRINT\***


\*For additional information on our Pb-Free strategy and soldering details, please download the **onsemi** Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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<b>DESCRIPTION:</b>	<b>WLCSP30, 2.46X2.06</b>	<b>PAGE 1 OF 29</b>

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